

TITLE OF INVENTION: OPEN CAVITY BRIDGE POWER DELIVERY
ARCHITECTURES AND PROCESSES

ABSTRACT

Embodiments disclosed herein include multi-die packages with open cavity bridges. In an example, an electronic apparatus includes a package substrate having alternating metallization layers and dielectric layers. The package substrate includes a first plurality of substrate pads and a second plurality of substrate pads, and an open cavity. A bridge die is in the open cavity, the bridge die including a first plurality of bridge pads, a second plurality of bridge pads, a power delivery bridge pad between the first plurality of bridge pads and the second plurality of bridge pads, and conductive traces. A first die is coupled to the first plurality of substrate pads and the first plurality of bridge pads. A second die is coupled to the second plurality of substrate pads and the second plurality of bridge pads. A power delivery conductive line is coupled to the power delivery bridge pad.

Fig. 1